US00D825499S

(12) United States Design Patent
Liu et al.

(10) **Patent No.: US D825,499 S**
(45) **Date of Patent: ** Aug. 14, 2018**

(54) **LIGHT EMITTING DIODE PACKAGE**

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(73) Assignee: **Genesis Photonics Inc.**, Tainan (TW)

(**) Term: **15 Years**

(21) Appl. No.: **29/598,778**

(22) Filed: **Mar. 28, 2017**

(30) **Foreign Application Priority Data**

Sep. 29, 2016 (TW) 105305761

(51) **LOC (11) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/180**
(58) **Field of Classification Search**
USPC D13/180; D26/1

(Continued)

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Primary Examiner — Selina Sikder
(74) *Attorney, Agent, or Firm* — JCIPRNET

(57) **CLAIM**

The ornamental design for a light emitting diode package, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a first embodiment of the light emitting diode package showing our new design;
FIG. **2** is a front view of the light emitting diode package of FIG. **1**;
FIG. **3** is a rear view of the light emitting diode package of FIG. **1**;
FIG. **4** is a left view of the light emitting diode package of FIG. **1**;
FIG. **5** is a right view of the light emitting diode package of FIG. **1**;
FIG. **6** is a top view of the light emitting diode package of FIG. **1**;
FIG. **7** is a bottom view of the light emitting diode package of FIG. **1**;
FIG. **8** is a perspective view of a second embodiment of the light emitting diode package showing our new design;
FIG. **9** is a front view of the light emitting diode package of FIG. **8**;
FIG. **10** is a rear view of the light emitting diode package of FIG. **8**;
FIG. **11** is a left view of the light emitting diode package of FIG. **8**;
FIG. **12** is a right view of the light emitting diode package of FIG. **8**;
FIG. **13** is a top view of the light emitting diode package of FIG. **8**;
FIG. **14** is a bottom view of the light emitting diode package of FIG. **8**;
FIG. **15** is a perspective view of a third embodiment of the light emitting diode package showing our new design;
FIG. **16** is a front view of the light emitting diode package of FIG. **15**;
FIG. **17** is a rear view of the light emitting diode package of FIG. **15**;

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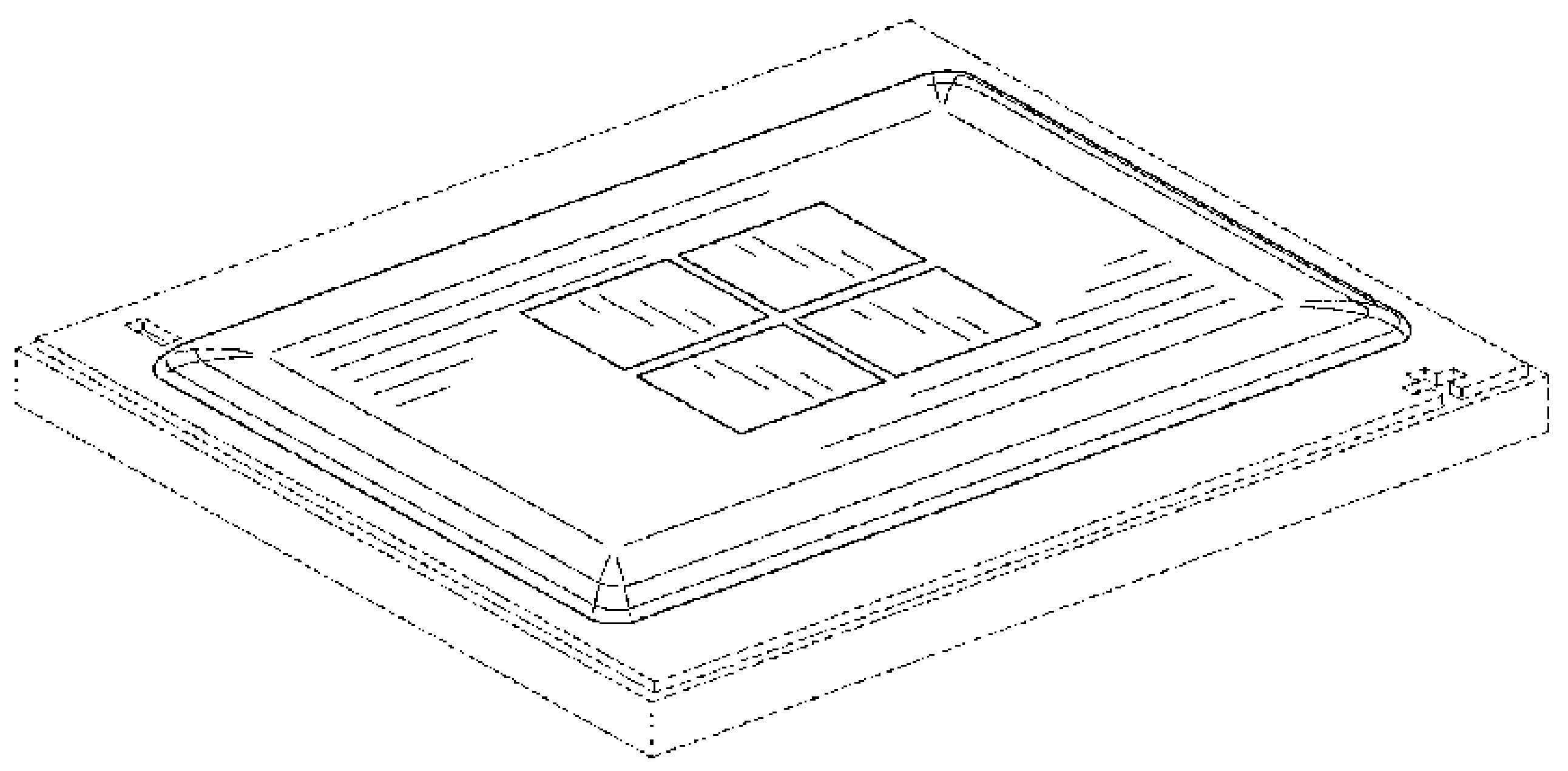

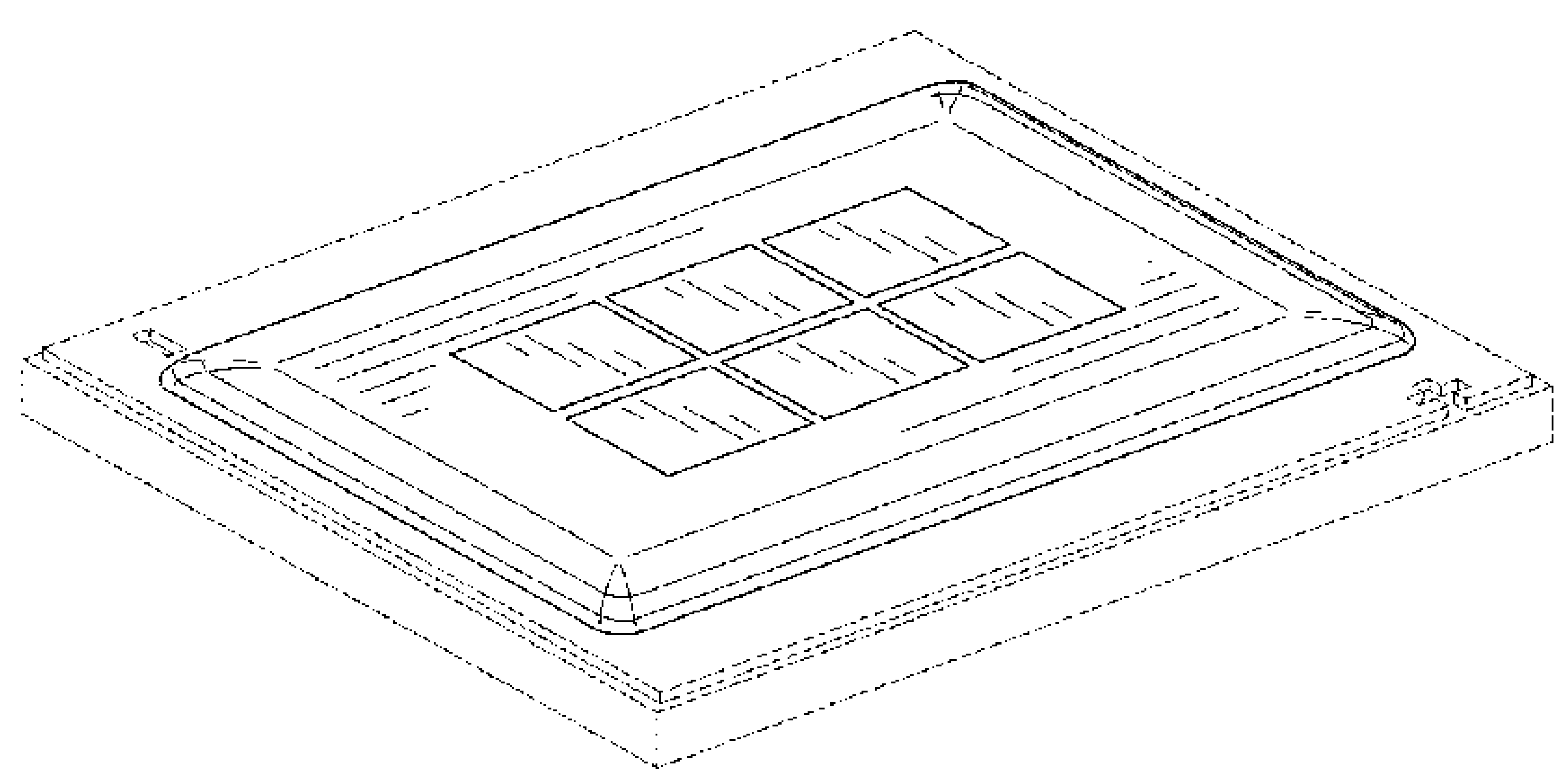

FIG. **18** is a left view of the light emitting diode package of FIG. **15**;

FIG. **19** is a right view of the light emitting diode package of FIG. **15**;

FIG. **20** is a top view of the light emitting diode package of FIG. **15**; and,

FIG. **21** is a bottom view of the light emitting diode package of FIG. **15**.

The broken lines in the drawings are included for the purpose of illustration and form no part of the claimed design.

1 Claim, 15 Drawing Sheets

(58) **Field of Classification Search**

CPC ... H01L 25/167; H01L 25/0753; H01L 27/15; H01L 27/156; H01L 31/02; H01L 33/00; H01L 33/04; H01L 33/08; H01L 33/10; H01L 33/20; H01L 33/38; H01L 33/42; H01L 33/48; H01L 33/62; H01L 33/483; H01L 33/486; F21K 9/00; F21K 9/30; F21K 9/54

See application file for complete search history.

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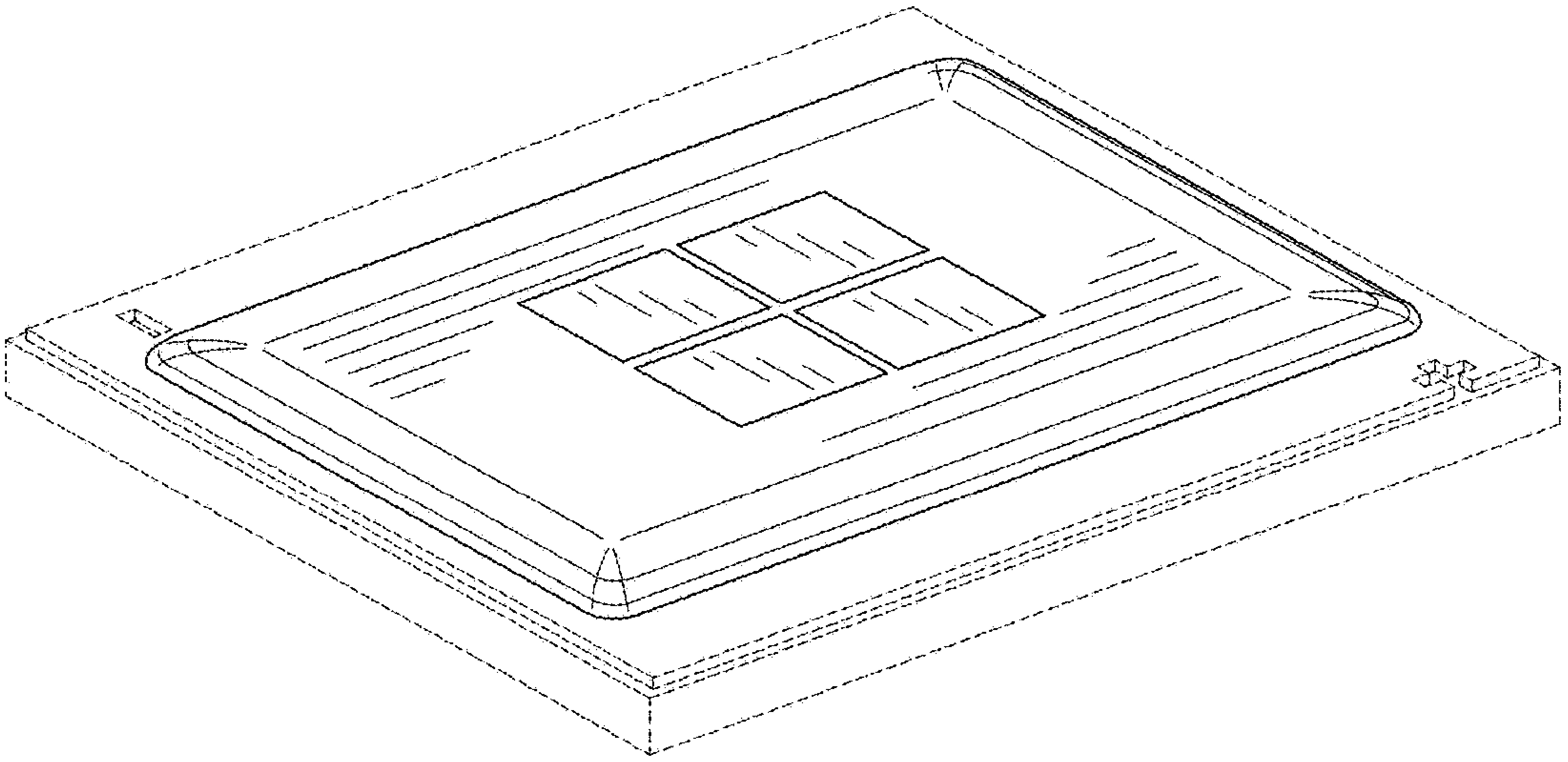


FIG. 1

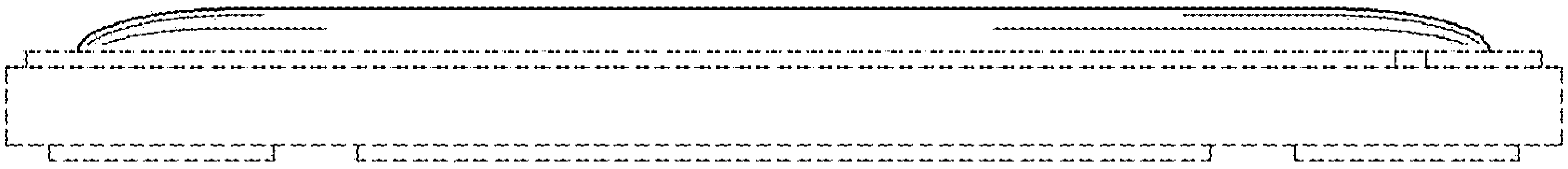
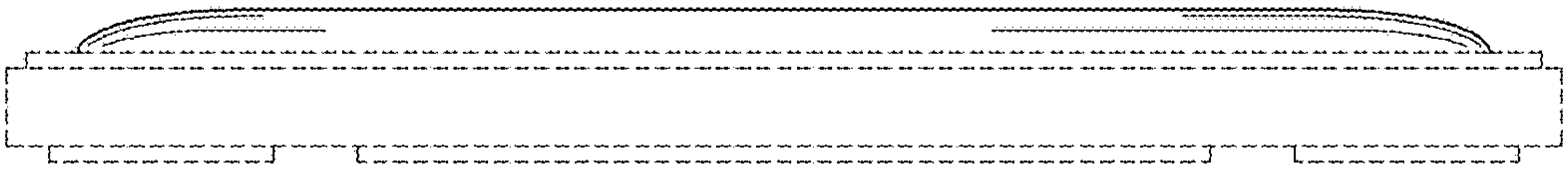


FIG. 2



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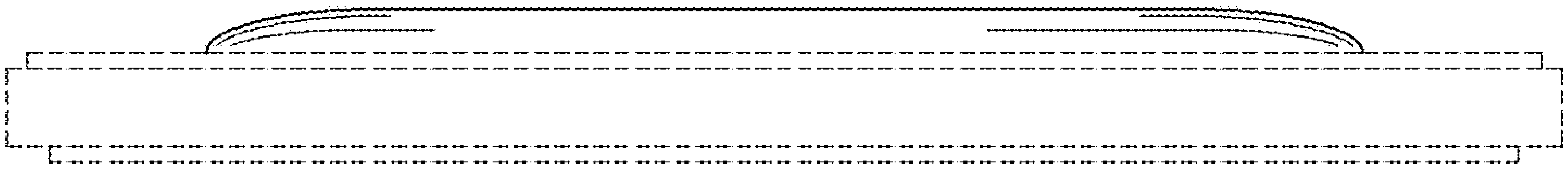

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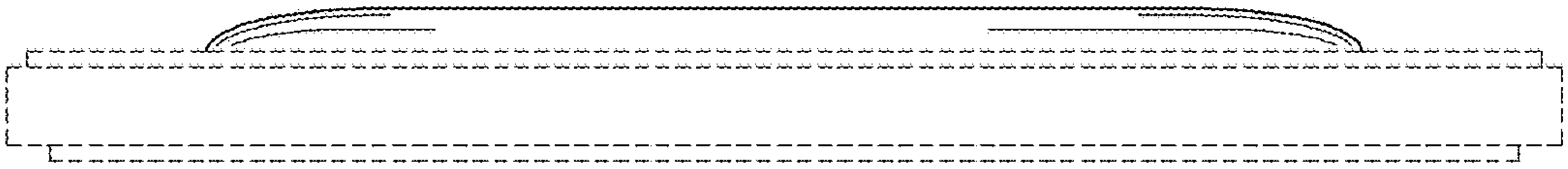

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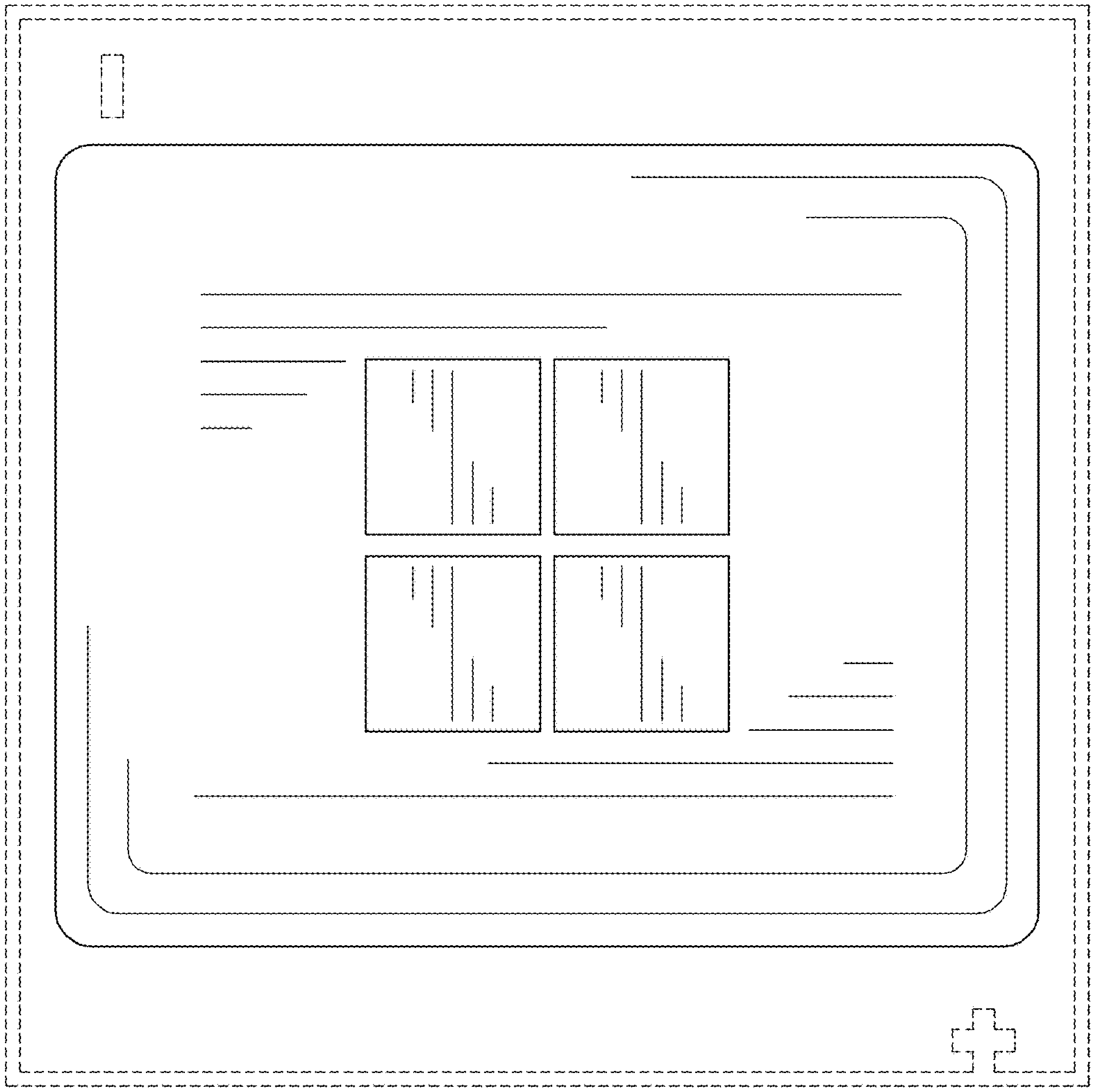

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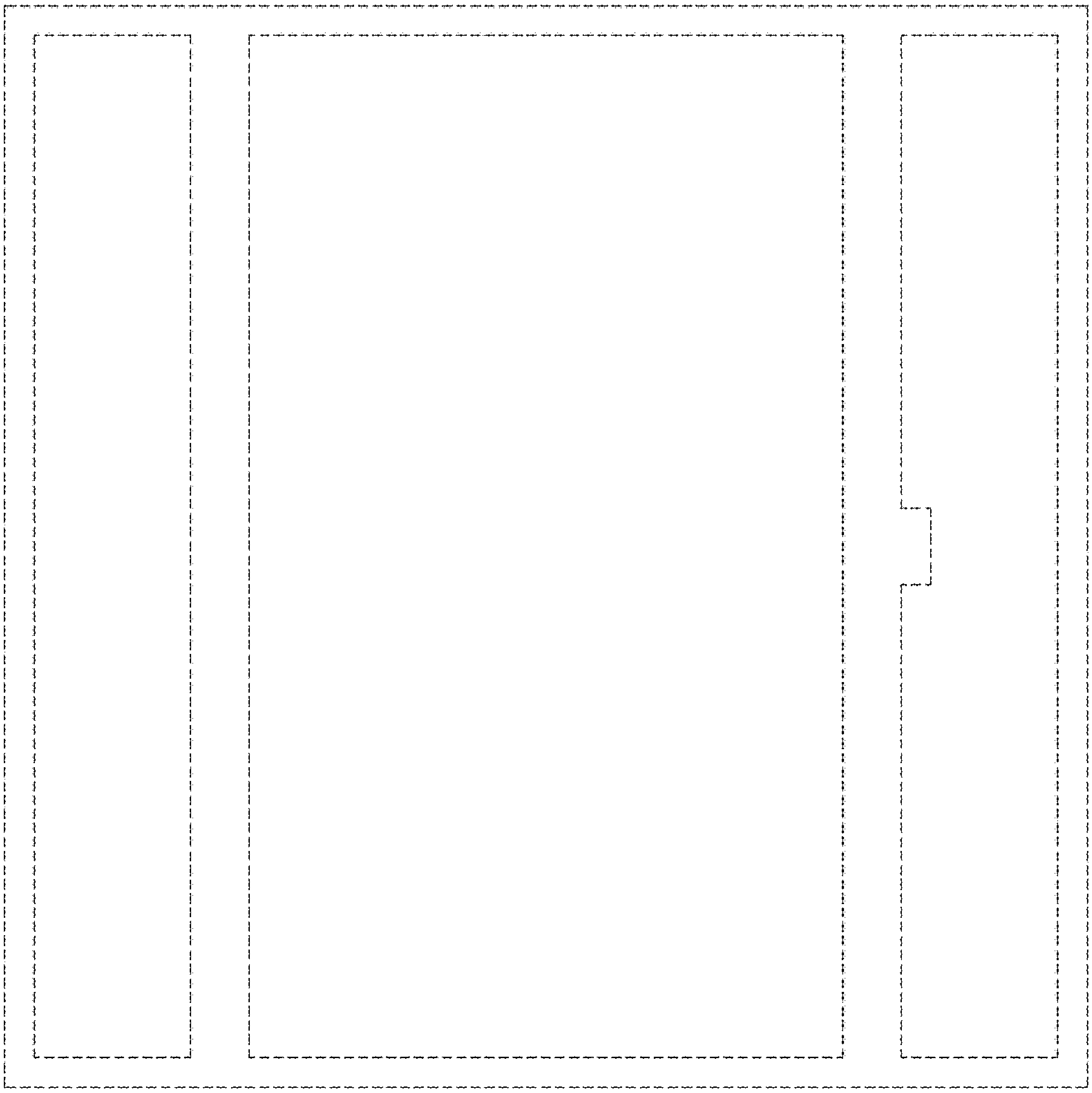

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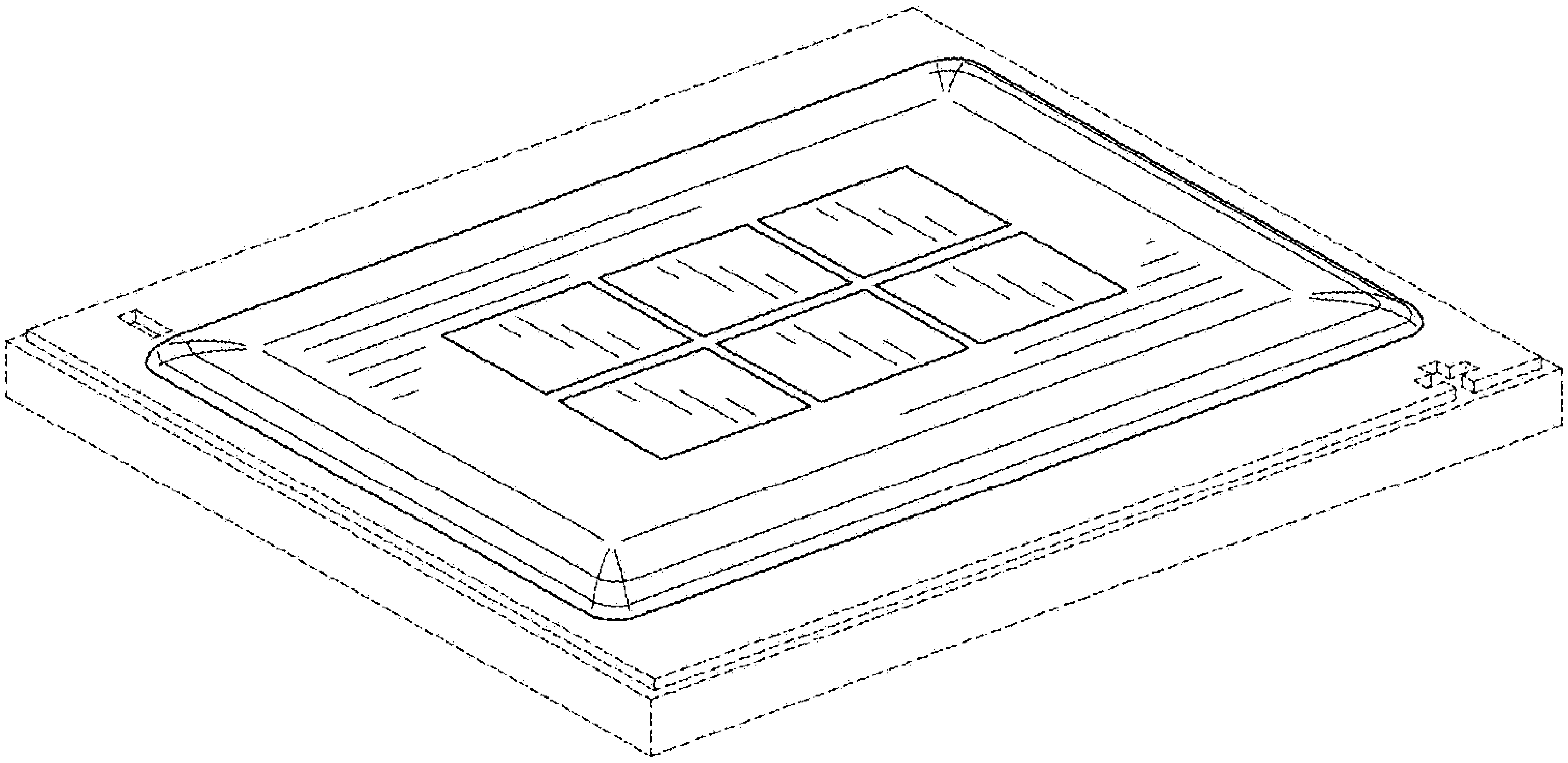


FIG. 8

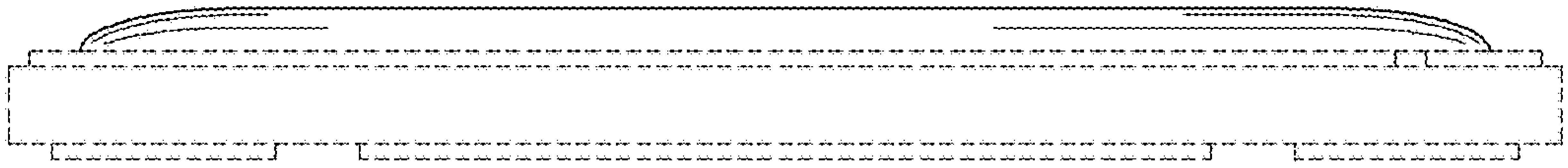


FIG. 9

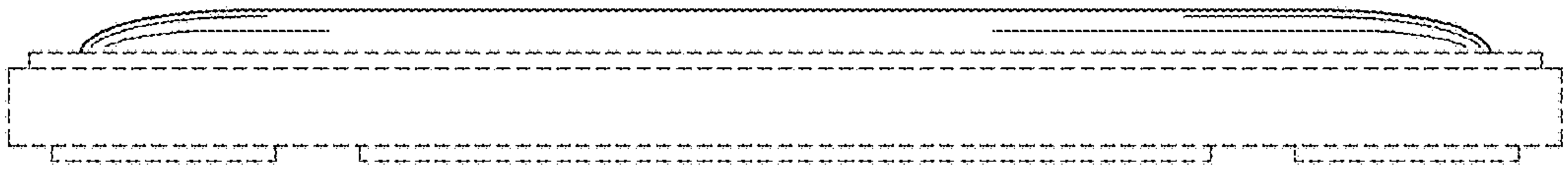
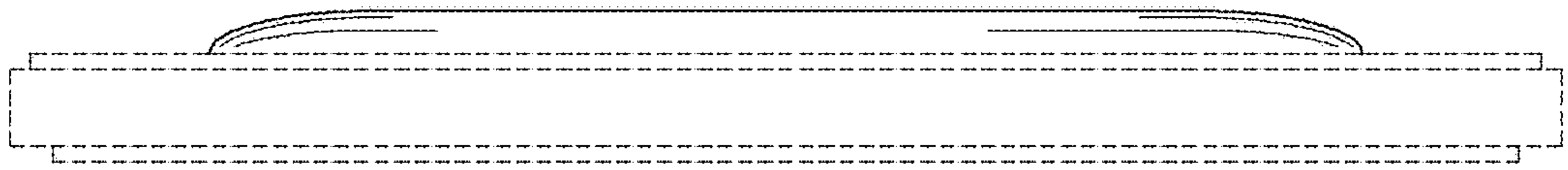


FIG. 10



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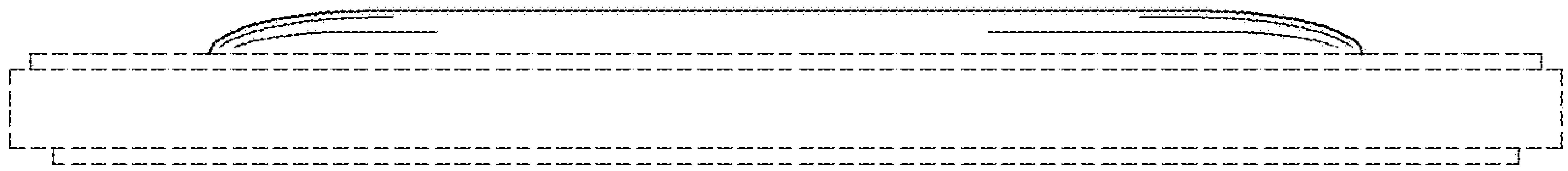

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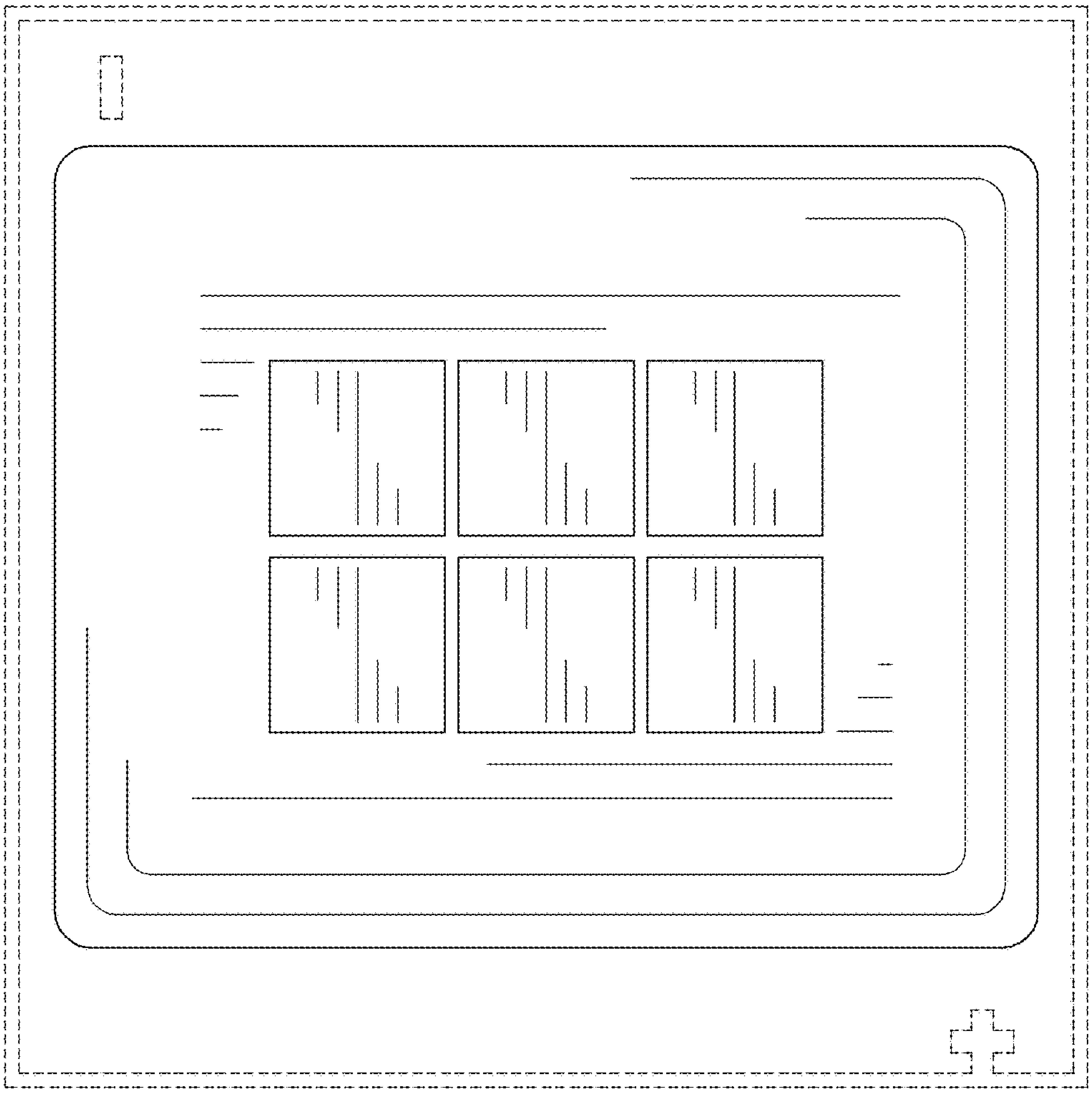

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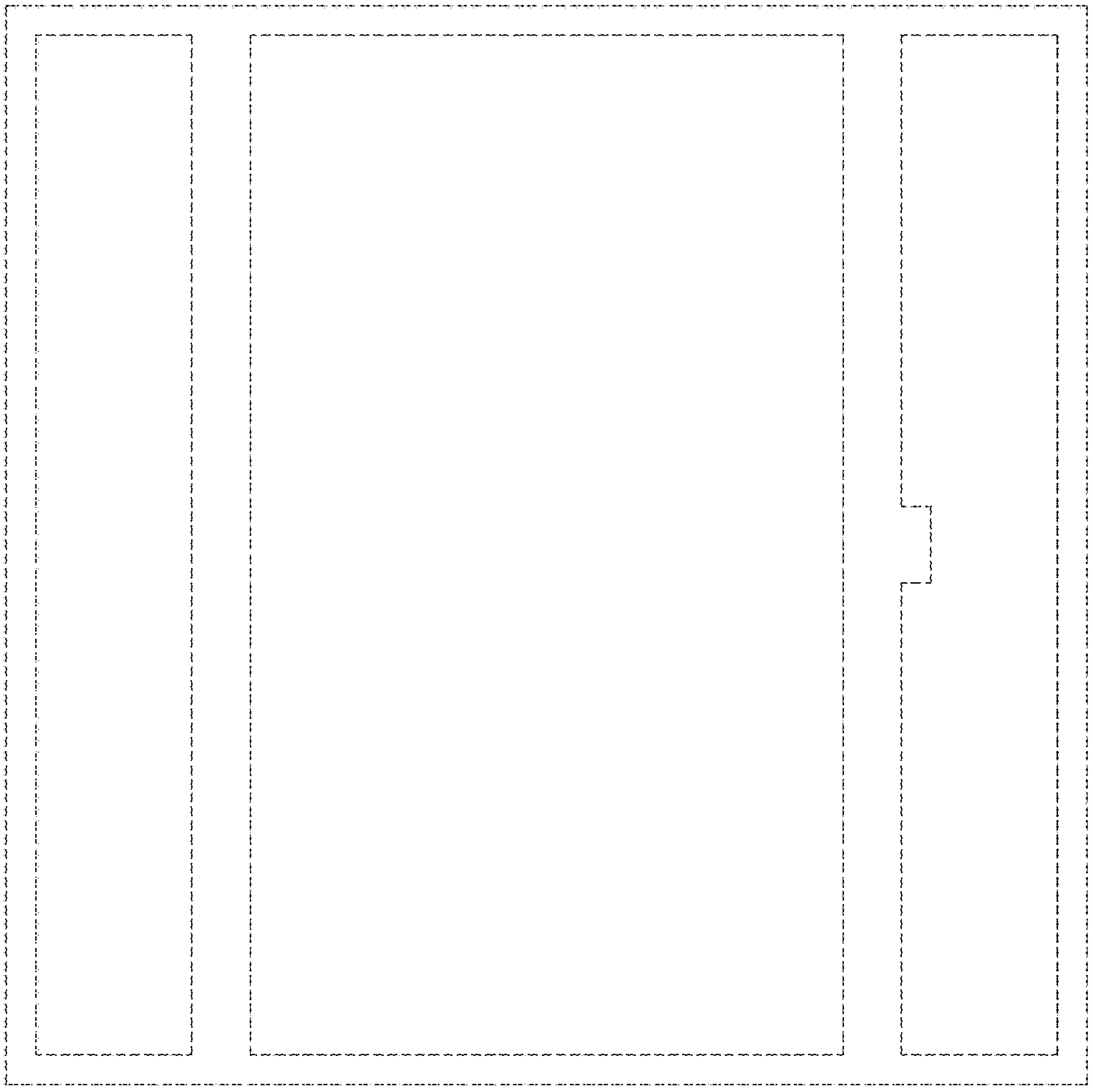

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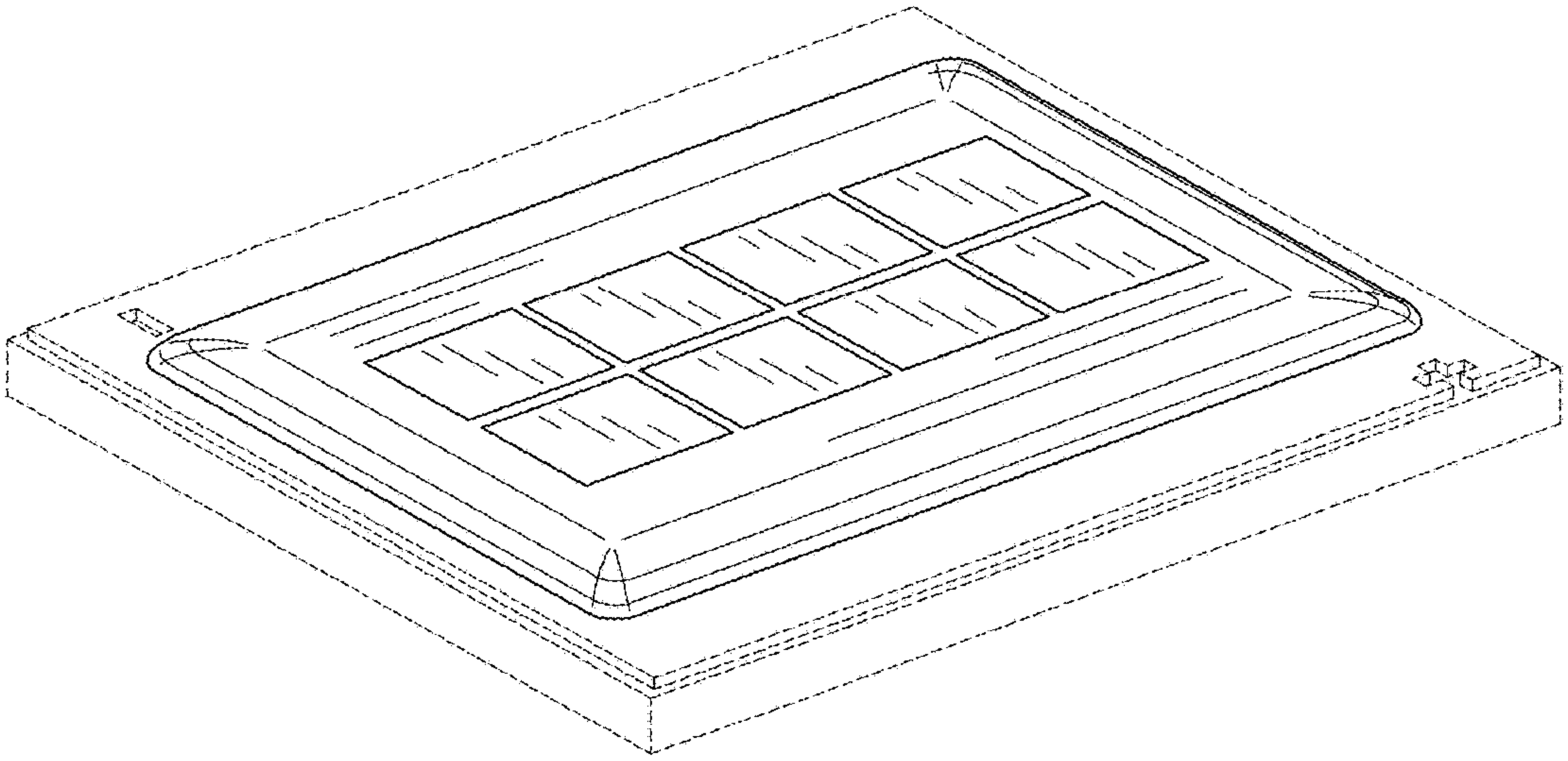

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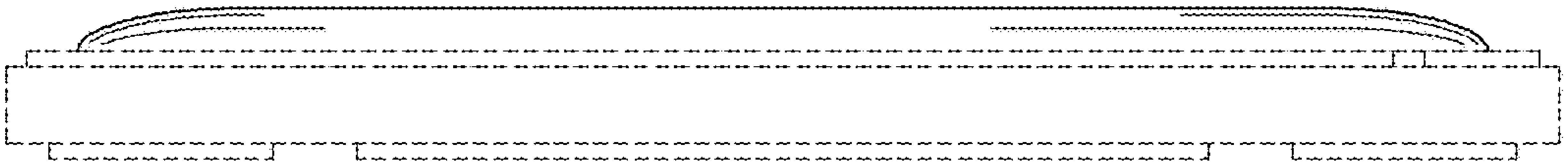


FIG. 16

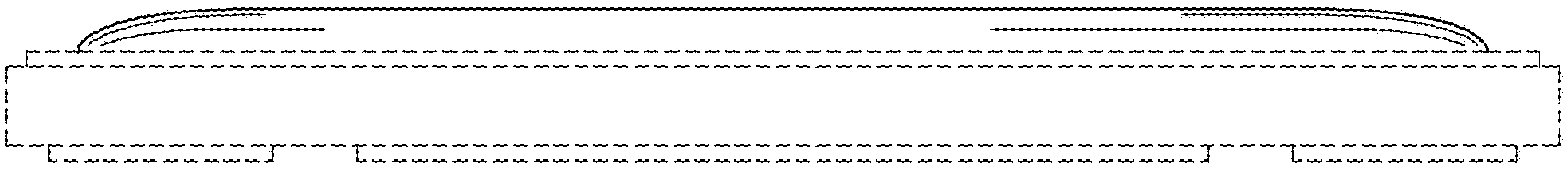
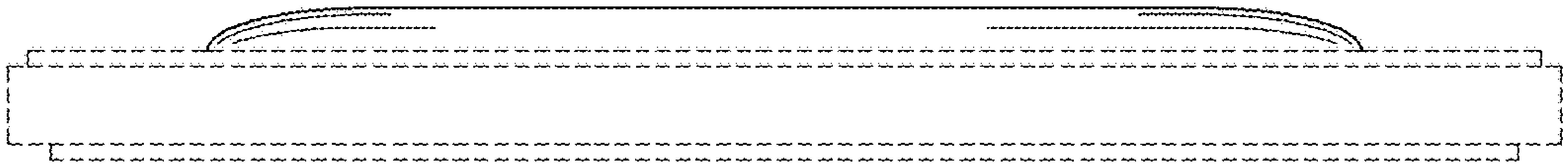


FIG. 17



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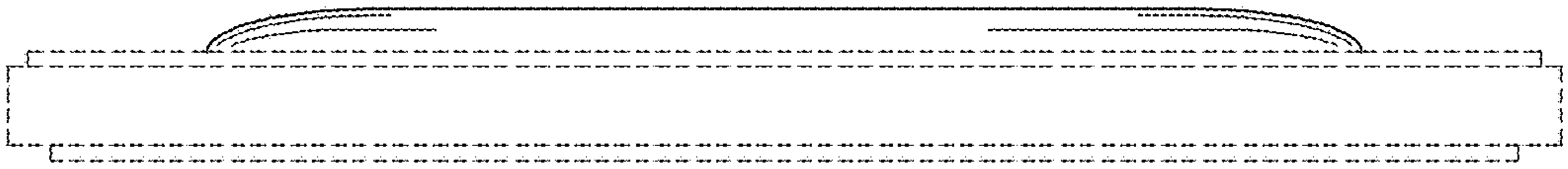

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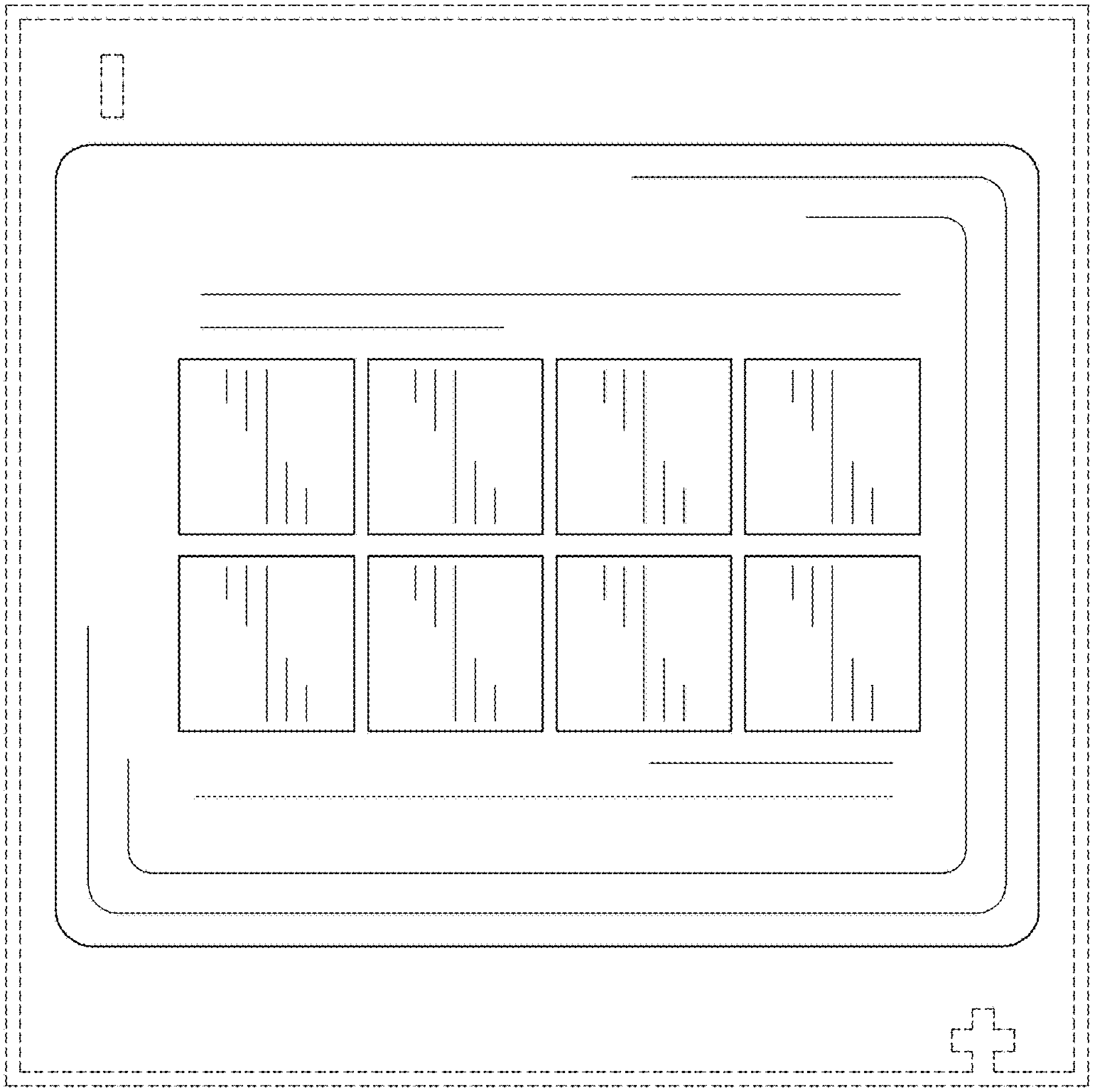

FIG. 20

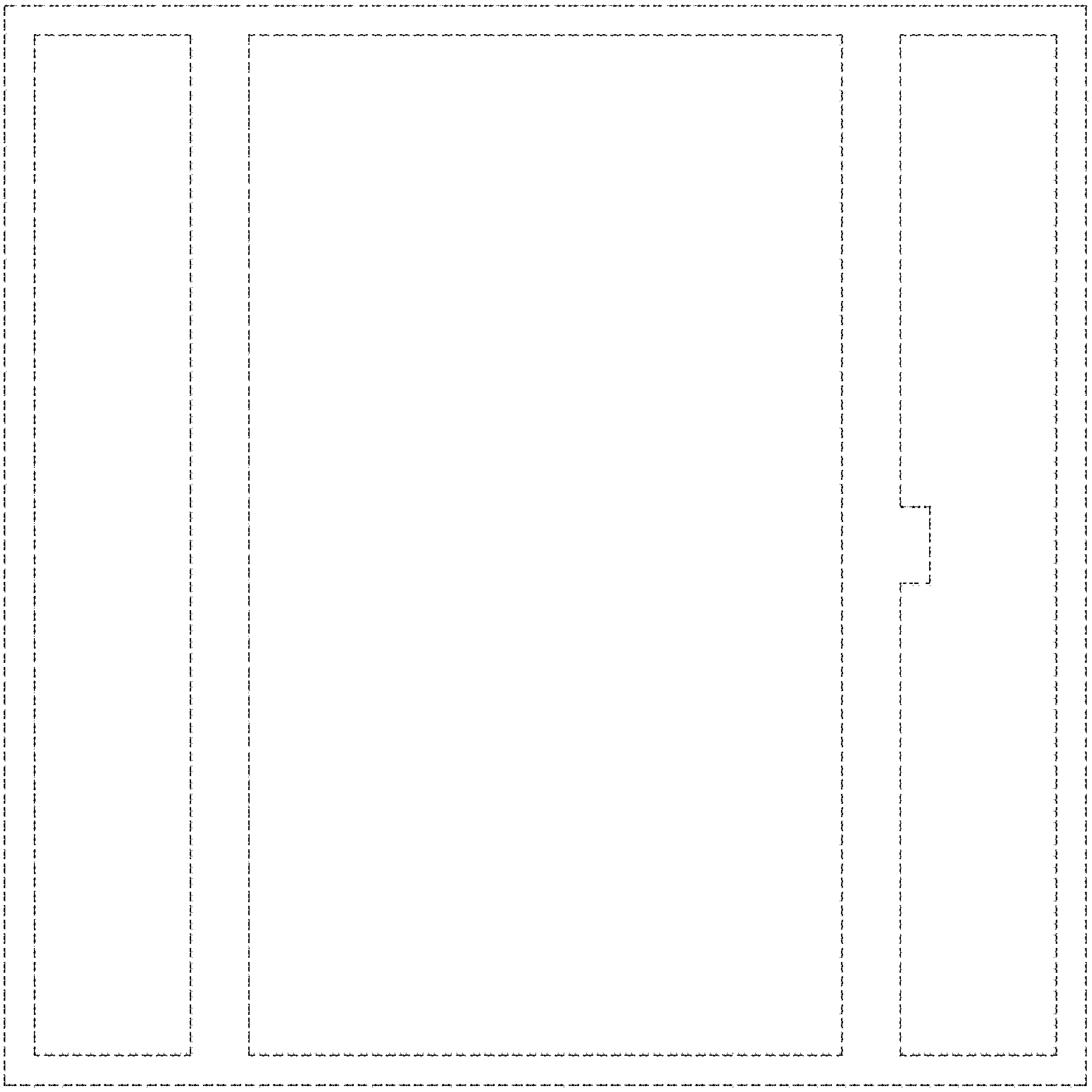

FIG. 21